



Bill of Materials

TI DESIGNS

TIPD165: Isolated, Shunt-Based Current Sensing Referen
Docking station BOM

Quantity	Designator	Value	Description	Manufacturer	PartNumber
1	C1	10u	CAP CER 6V3 10% X5R 0805	Taiyo Yuden	JMK212BJ106KD-T
2	C2 C4	100n	CAP CER 6V3 10% X7R 0805	Kemet	C0805C104K9RACTU
1	C3	4u7	CAP CER 6V3 10% X5R 0805	Taiyo Yuden	JMK212BJ475KG-T
2	C5-6	470n	CAP CER 6V3 10% X7R 0805	TDK Corporation	CGJ4J2X7R0J474K125AA
1	D1	GREEN	LED GREEN 0805 SMD, Diffused, 567nm	Stanley Electric Co	PG1112H-TR
1	J1		CONN PWR JACK 2.5X5.5MM HIGH CUR	CUI Inc	PJ-002BH
1	J2		Header, Male, 7x2-pin, 100mil spacing, remove pin 6	FCI	67996-114HLF
1	J3		180 pin (120 + 60) HSEC8 socket	Samtec	HSEC8-130-01-L-DV-A & HSEC8-160-01-L-DV-A-BL
1	J4		Header, Male, 1x17-pin, 100mil spacing	Harwin Inc	M20-9731746
1	J5		Header, Male, 1x15-pin, 100mil spacing	Harwin Inc	M20-9991546
2	J6-7		Header, Male, 1x32-pin, 100mil spacing	Harwin Inc	M20-9993246
1	J8		Header, Male, 1x27-pin, 100mil spacing	Harwin Inc	M20-9992746
1	J9		Header, Male, 1x26-pin, 100mil spacing	Harwin Inc	M20-9992646
8	J10-11 J14-15 J18 J20 J22 J24		Header, Male, 1x4-pin, 100mil spacing	3M	961104-6404-AR
7	J12-13 J16 J19 J21 J23 J25		Header, Male, 1x2-pin, 100mil spacing	3M	961102-6404-AR
1	J17		CONN RECEPT MINI USB2.0 5POS	Hirose Electric Co Ltd	UX60-MB-5ST
1	R1	470R	RES 1/8W 5% 0805 SMD	Stackpole Electronics Inc	RMCF0805JT470R
1	S1		Toggle Switches SPDT ON-ON PC MOUNT	E-Switch	200AWMSP1T1A1M2QE
1	U1		IC LDO REG 3.3V 500MA SOT223-6	Texas Instruments	TPS79533DCQ

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